



## Press Release

**Media Contact:**  
Laura Mawbey  
VP Sales and Contracts  
509-667-5122  
lmawbey@pacaero.com

### **PA&E Announces Hermetic Mate for Souriau's *microComp*<sup>®</sup> Connector Series**

*New Option for Applications Where Size, Weight and Hermetic Performance are Key Considerations*

**Wenatchee, WA – October 9, 2008** -- Souriau's innovative *microComp* series of high-density, light-weight, space-saving rectangular connectors can now be deployed in applications that require a hermetic seal, thanks to PA&E's new hermetic *microComp* mate.

"The *microComp* connector series offers a number of unique features, but it wasn't an option for engineers designing components that required hermetic sealing," said Ed Phinney, Vice President of Engineering at PA&E. "We partnered with Souriau, and leveraged our expertise in ceramic-to-metal sealing technology, to create a hermetic mate for the *microComp* line that gives design engineers working in the space and defense industries a new, high-performance, hermetic connector option."

Souriau's *microComp* connector line is well suited to any application that requires a light-weight, high-density rectangular connector. It weighs 60% less and is 25% smaller than standard high-density Sub-D connectors. It can be built with as few as seven or as many as 104 contacts with a contact pitch of 2.0 x 1.7 mm<sup>2</sup>. The *microComp* line comes in both space and military grade configurations and each connector offers dismountable contact construction for wiring flexibility

The PA&E *microComp* hermetic mate can be built to match any *microComp* configuration. It has a leak rate of less than 1X10<sup>-9</sup> cc/second helium at one atmospheric differential pressure thanks to PA&E's proprietary Kryoflex<sup>®</sup>

polycrystalline ceramic. Kryoflex-sealed connectors provide superior electrical performance -- up to 70 times the current-carrying capacity of conventional products -- while withstanding extreme mechanical and thermal stresses.

These connectors provide an insulation resistance of greater than 5,000 megohms at 500 VDC when tested in IAW MIL-STD 1344, Method 3003. They are built with beryllium copper alloy contacts that are finished in nickel/gold. The *microComp* mate is designed for aluminum, titanium or iron/nickel alloy applications and has an operating temperature range of -65° C to 200° C.

For more information about PA&E's custom interconnect products, integrated electronic packaging capabilities or EMI filters product line, contact the company at 509-664-8000 or visit at <http://www.pacaero.com>.

*PA&E, Inc. is an integrated manufacturing company, specializing in technically demanding ceramic and metal components and assemblies, hermetic connectors and advanced micro-electronic hermetic packaging for global leaders in the defense, space, medical and commercial industries. PA&E is ISO 9001:2000/AS9100 Rev B certified and NADCAP compliant.*

**PA&E – 434 Olds Station Road – Wenatchee, WA – 98801 – Tel: 509-664-8000 – Fax: 509-664-6868**

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